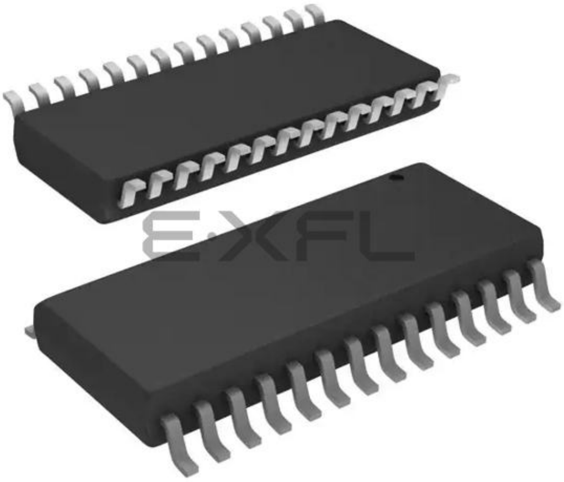
Microchip Technology - PIC24EP512GP202-I/SO Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

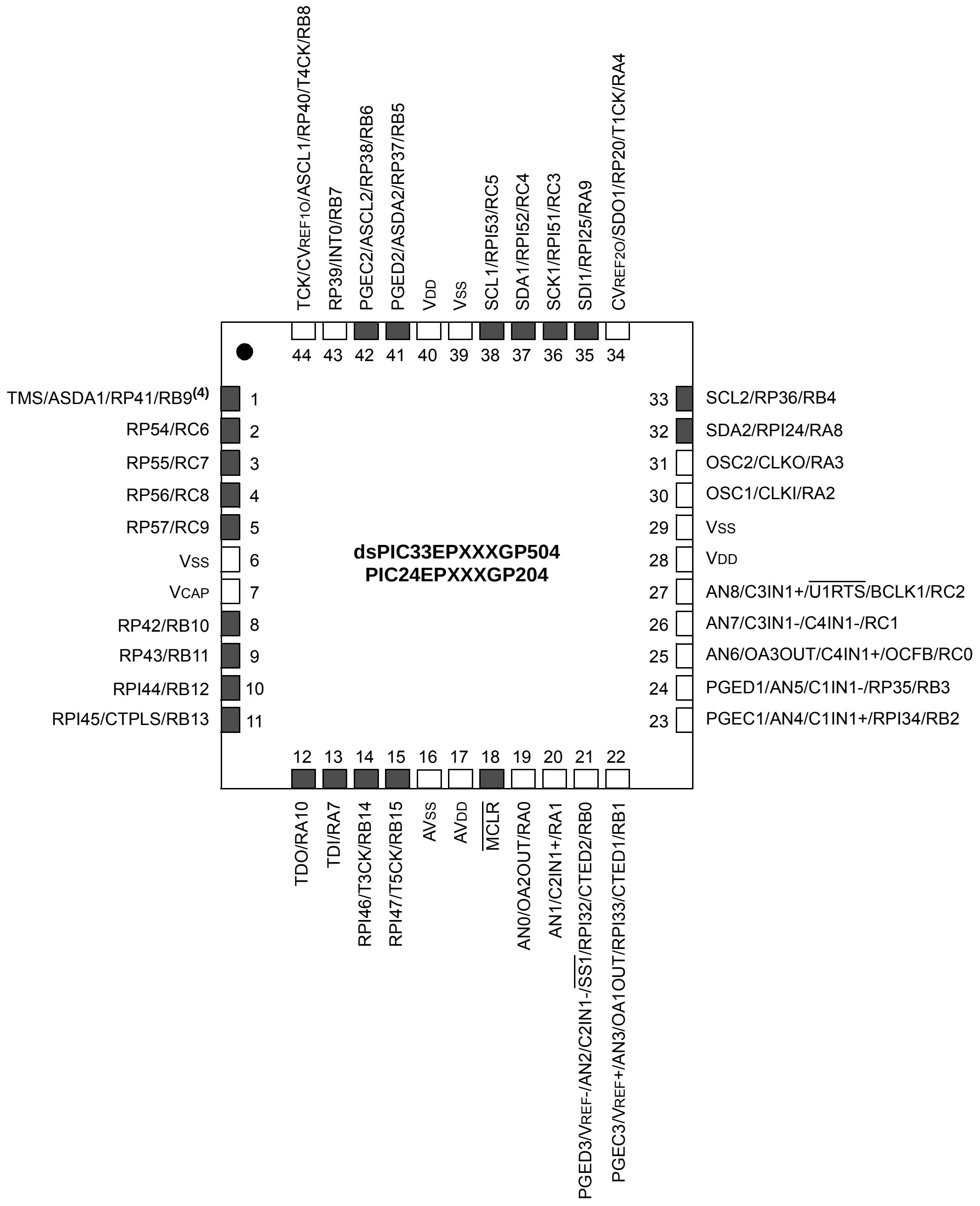
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep512gp202-i-so

Pin Diagrams (Continued)

44-Pin QFN[1,2,3]

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 “Peripheral Pin Select (PPS)”** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 “I/O Ports”** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the “Communication Channel Select” (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *“Using MPLAB® ICD 3”* (poster) DS51765
- *“MPLAB® ICD 3 Design Advisory”* DS51764
- *“MPLAB® REAL ICE™ In-Circuit Emulator User’s Guide”* DS51616
- *“Using MPLAB® REAL ICE™ In-Circuit Emulator”* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 “Oscillator Configuration”** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT

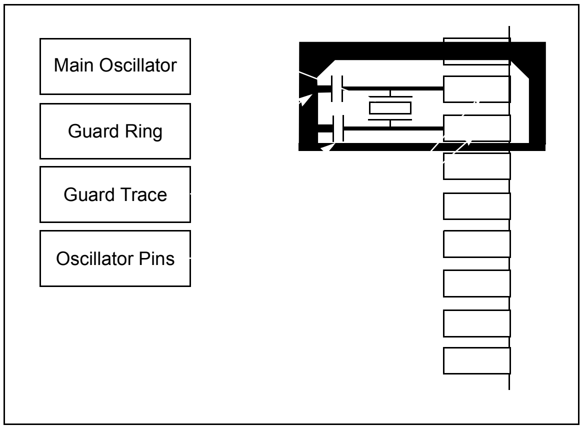


TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
SR	0042	OA	OB	SA	SB	OAB	SAB	DA	DC	IPL2	IPL1	IPL0	RA	N	OV	Z	C	`0000`
CORCON	0044	VAR	—	US<1:0>		EDT	DL<2:0>			SATA	SATB	SATDW	ACCSAT	IPL3	SFA	RND	IF	`0020`
MODCON	0046	XMODEN	YMODEN	—	—	BWM<3:0>				YWM<3:0>				XWM<3:0>				`0000`
XMODSRT	0048	XMODSRT<15:0>															—	`0000`
XMODEND	004A	XMODEND<15:0>															—	`0001`
YMODSRT	004C	YMODSRT<15:0>															—	`0000`
YMODEND	004E	YMODEND<15:0>															—	`0001`
XBREV	0050	BREN	XBREV<14:0>															`0000`
DISICNT	0052	—	—	DISICNT<13:0>														`0000`
TBLPAG	0054	—	—	—	—	—	—	—	—	TBLPAG<7:0>								`0000`
MSTRPR	0058	MSTRPR<15:0>																`0000`

Legend: `x` = unknown value on Reset, — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-3: INTERRUPT CONTROLLER REGISTER MAP FOR PIC24EPXXXGP20X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IFS0	0800	—	DMA1IF	AD1IF	U1TXIF	U1RXIF	SPI1IF	SPI1EIF	T3IF	T2IF	OC2IF	IC2IF	DMA0IF	T1IF	OC1IF	IC1IF	INT0IF	0000
IFS1	0802	U2TXIF	U2RXIF	INT2IF	T5IF	T4IF	OC4IF	OC3IF	DMA2IF	—	—	—	INT1IF	CNIF	CMIF	MI2C1IF	SI2C1IF	0000
IFS2	0804	—	—	—	—	—	—	—	—	—	IC4IF	IC3IF	DMA3IF	—	—	SPI2IF	SPI2EIF	0000
IFS3	0806	—	—	—	—	—	—	—	—	—	—	—	—	—	MI2C2IF	SI2C2IF	—	0000
IFS4	0808	—	—	CTMUIF	—	—	—	—	—	—	—	—	—	CRCIF	U2EIF	U1EIF	—	0000
IFS8	0810	JTAGIF	ICDIF	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IFS9	0812	—	—	—	—	—	—	—	—	—	PTG3IF	PTG2IF	PTG1IF	PTG0IF	PTGWDTIF	PTGSTEPIF	—	0000
IEC0	0820	—	DMA1IE	AD1IE	U1TXIE	U1RXIE	SPI1IE	SPI1EIE	T3IE	T2IE	OC2IE	IC2IE	DMA0IE	T1IE	OC1IE	IC1IE	INT0IE	0000
IEC1	0822	U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE	—	—	—	INT1IE	CNIE	CMIE	MI2C1IE	SI2C1IE	0000
IEC2	0824	—	—	—	—	—	—	—	—	—	IC4IE	IC3IE	DMA3IE	—	—	SPI2IE	SPI2EIE	0000
IEC3	0826	—	—	—	—	—	—	—	—	—	—	—	—	—	MI2C2IE	SI2C2IE	—	0000
IEC4	0828	—	—	CTMUIE	—	—	—	—	—	—	—	—	—	CRCIE	U2EIE	U1EIE	—	0000
IEC8	0830	JTAGIE	ICDIE	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
IEC9	0832	—	—	—	—	—	—	—	—	—	PTG3IE	PTG2IE	PTG1IE	PTG0IE	PTGWDTIE	PTGSTEPIE	—	0000
IPC0	0840	—	T1IP<2:0>			—	OC1IP<2:0>			—	IC1IP<2:0>			—	INT0IP<2:0>			4444
IPC1	0842	—	T2IP<2:0>			—	OC2IP<2:0>			—	IC2IP<2:0>			—	DMA0IP<2:0>			4444
IPC2	0844	—	U1RXIP<2:0>			—	SPI1IP<2:0>			—	SPI1EIP<2:0>			—	T3IP<2:0>			4444
IPC3	0846	—	—	—	—	—	DMA1IP<2:0>			—	AD1IP<2:0>			—	U1TXIP<2:0>			0444
IPC4	0848	—	CNIP<2:0>			—	CMIP<2:0>			—	MI2C1IP<2:0>			—	SI2C1IP<2:0>			4444
IPC5	084A	—	—	—	—	—	—	—	—	—	—	—	—	—	INT1IP<2:0>			0004
IPC6	084C	—	T4IP<2:0>			—	OC4IP<2:0>			—	OC3IP<2:0>			—	DMA2IP<2:0>			4444
IPC7	084E	—	U2TXIP<2:0>			—	U2RXIP<2:0>			—	INT2IP<2:0>			—	T5IP<2:0>			4444
IPC8	0850	—	—	—	—	—	—	—	—	—	SPI2IP<2:0>			—	SPI2EIP<2:0>			0044
IPC9	0852	—	—	—	—	—	IC4IP<2:0>			—	IC3IP<2:0>			—	DMA3IP<2:0>			0444
IPC12	0858	—	—	—	—	—	MI2C2IP<2:0>			—	SI2C2IP<2:0>			—	—	—	—	0440
IPC16	0860	—	CRCIP<2:0>			—	U2EIP<2:0>			—	U1EIP<2:0>			—	—	—	—	4440
IPC19	0866	—	—	—	—	—	—	—	—	—	CTMUIP<2:0>			—	—	—	—	0040
IPC35	0886	—	JTAGIP<2:0>			—	ICDIP<2:0>			—	—	—	—	—	—	—	—	4400
IPC36	0888	—	PTG0IP<2:0>			—	PTGWDTIP<2:0>			—	PTGSTEPIP<2:0>			—	—	—	—	4440
IPC37	088A	—	—	—	—	—	PTG3IP<2:0>			—	PTG2IP<2:0>			—	PTG1IP<2:0>			0444
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	—	—	—	—	—	—	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-21: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = `0` OR `1` FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1CTRL1	0400	—	—	CSIDL	ABAT	CANCKS	REQOP<2:0>			OPMODE<2:0>			—	CANCAP	—	—	WIN	0480
C1CTRL2	0402	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C1VEC	0404	—	—	—	FILHIT<4:0>					—	ICODE<6:0>							0040
C1FCTRL	0406	DMABS<2:0>			—	—	—	—	—	—	—	—	FSA<4:0>					0000
C1FIFO	0408	—	—	FBP<5:0>						—	—	FNRB<5:0>						0000
C1INTF	040A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C1INTE	040C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C1EC	040E	TERRCNT<7:0>								RERRCNT<7:0>								0000
C1CFG1	0410	—	—	—	—	—	—	—	—	SJW<1:0>		BRP<5:0>						0000
C1CFG2	0412	—	WAKFIL	—	—	—	SEG2PH<2:0>			SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>			0000
C1FEN1	0414	FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8	FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0	FFFF
C1FMSKSEL1	0418	F7MSK<1:0>		F6MSK<1:0>		F5MSK<1:0>		F4MSK<1:0>		F3MSK<1:0>		F2MSK<1:0>		F1MSK<1:0>		F0MSK<1:0>		0000
C1FMSKSEL2	041A	F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>		F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>		0000

Legend: — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

TABLE 4-22: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = `0` FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1RXFUL1	0420	RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8	RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0	0000
C1RXFUL2	0422	RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24	RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16	0000
C1RXOVF1	0428	RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8	RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0	0000
C1RXOVF2	042A	RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24	RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16	0000
C1TR01CON	0430	TXEN1	TXABT1	TXLARB1	TXERR1	TXREQ1	RTREN1	TX1PRI<1:0>		TXEN0	TXABAT0	TXLARB0	TXERR0	TXREQ0	RTREN0	TX0PRI<1:0>		0000
C1TR23CON	0432	TXEN3	TXABT3	TXLARB3	TXERR3	TXREQ3	RTREN3	TX3PRI<1:0>		TXEN2	TXABAT2	TXLARB2	TXERR2	TXREQ2	RTREN2	TX2PRI<1:0>		0000
C1TR45CON	0434	TXEN5	TXABT5	TXLARB5	TXERR5	TXREQ5	RTREN5	TX5PRI<1:0>		TXEN4	TXABAT4	TXLARB4	TXERR4	TXREQ4	RTREN4	TX4PRI<1:0>		0000
C1TR67CON	0436	TXEN7	TXABT7	TXLARB7	TXERR7	TXREQ7	RTREN7	TX7PRI<1:0>		TXEN6	TXABAT6	TXLARB6	TXERR6	TXREQ6	RTREN6	TX6PRI<1:0>		xxxx
C1RXD	0440	ECAN1 Receive Data Word																xxxx
C1TXD	0442	ECAN1 Transmit Data Word																xxxx

Legend: `x` = unknown value on Reset, — = unimplemented, read as ‘`0`’. Reset values are shown in hexadecimal.

REGISTER 5-1: NVMCON: NONVOLATILE MEMORY (NVM) CONTROL REGISTER

R/SO-0[1]	R/W-0[1]	R/W-0[1]	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	NVMSIDL[2]	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0[1]	R/W-0[1]	R/W-0[1]	R/W-0[1]
—	—	—	—	NVMOP3[3,4]	NVMOP2[3,4]	NVMOP1[3,4]	NVMOP0[3,4]
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit[1]

`1` = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
`0` = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit[1]

`1` = Enables Flash program/erase operations
`0` = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit[1]

`1` = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit)
`0` = The program or erase operation completed normally

bit 12 **NVMSIDL:** NVM Stop in Idle Control bit[2]

`1` = Flash voltage regulator goes into Standby mode during Idle mode
`0` = Flash voltage regulator is active during Idle mode

bit 11-4 **Unimplemented:** Read as ‘`0`’

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits[1,3,4]

`1111` = Reserved
`1110` = Reserved
`1101` = Reserved
`1100` = Reserved
`1011` = Reserved
`1010` = Reserved
`0011` = Memory page erase operation
`0010` = Reserved
`0001` = Memory double-word program operation[5]
`0000` = Reserved

Note 1: These bits can only be reset on a POR.
2: If this bit is set, there will be minimal power savings (I_{IDLE}) and upon exiting Idle mode, there is a delay (T_{VREG}) before Flash memory becomes operational.
3: All other combinations of NVMOP<3:0> are unimplemented.
4: Execution of the `PWRSAV` instruction is ignored while any of the NVM operations are in progress.
5: Two adjacent words on a 4-word boundary are programmed during execution of this operation.

REGISTER 17-2: QEI1IOC: QEI1 I/O CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QCAPEN	FLTREN	QFDIV2	QFDIV1	QFDIV0	OUTFNC1	OUTFNC0	SWPAB
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R-x	R-x	R-x	R-x
HOMPOL	IDXPOL	QEBPOL	QEAPOL	HOME	INDEX	QEB	QEA
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **QCAPEN:** QEI Position Counter Input Capture Enable bit
1 = Index match event triggers a position capture event
0 = Index match event does not trigger a position capture event

bit 14 **FLTREN:** QEAx/QEBx/INDXx/HOMEx Digital Filter Enable bit
1 = Input pin digital filter is enabled
0 = Input pin digital filter is disabled (bypassed)

bit 13-11 **QFDIV<2:0>:** QEAx/QEBx/INDXx/HOMEx Digital Input Filter Clock Divide Select bits
111 = 1:128 clock divide
110 = 1:64 clock divide
101 = 1:32 clock divide
100 = 1:16 clock divide
011 = 1:8 clock divide
010 = 1:4 clock divide
001 = 1:2 clock divide
000 = 1:1 clock divide

bit 10-9 **OUTFNC<1:0>:** QEI Module Output Function Mode Select bits
11 = The CTNCMPx pin goes high when QEI1LEC ≥ POS1CNT ≥ QEI1GEC
10 = The CTNCMPx pin goes high when POS1CNT ≤ QEI1LEC
01 = The CTNCMPx pin goes high when POS1CNT ≥ QEI1GEC
00 = Output is disabled

bit 8 **SWPAB:** Swap QEA and QEB Inputs bit
1 = QEAx and QEBx are swapped prior to quadrature decoder logic
0 = QEAx and QEBx are not swapped

bit 7 **HOMPOL:** HOMEx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

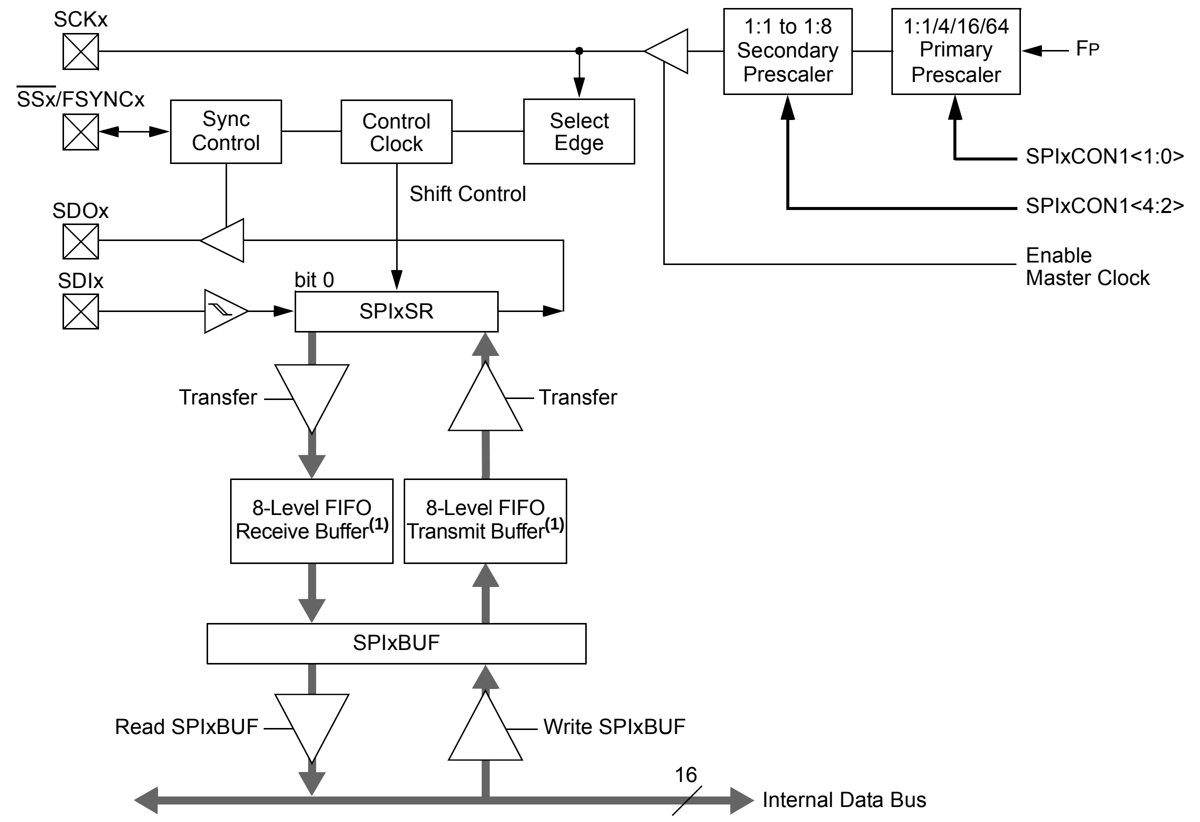
bit 6 **IDXPOL:** INDXx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 5 **QEBPOL:** QEBx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 4 **QEAPOL:** QEAx Input Polarity Select bit
1 = Input is inverted
0 = Input is not inverted

bit 3 **HOME:** Status of HOMEx Input Pin After Polarity Control
1 = Pin is at logic ‘1’
0 = Pin is at logic ‘0’

FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



Note 1: In Standard mode, the FIFO is only one level deep.

22.2 CTMU Control Registers

REGISTER 22-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN(1)	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.)
0 = Software is used to trigger edges (manual set of EDGxSTAT)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(1)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** ADC Trigger Control bit
1 = CTMU triggers ADC start of conversion
0 = CTMU does not trigger ADC start of conversion

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: The ADC module Sample-and-Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

REGISTER 23-1: AD1CON1: ADC1 CONTROL REGISTER 1 (CONTINUED)

bit 7-5	**SSRC<2:0>:** Sample Trigger Source Select bits If SSRCG = `1`: `111` = Reserved `110` = PTGO15 primary trigger compare ends sampling and starts conversion[1] `101` = PTGO14 primary trigger compare ends sampling and starts conversion[1] `100` = PTGO13 primary trigger compare ends sampling and starts conversion[1] `011` = PTGO12 primary trigger compare ends sampling and starts conversion[1] `010` = PWM Generator 3 primary trigger compare ends sampling and starts conversion[2] `001` = PWM Generator 2 primary trigger compare ends sampling and starts conversion[2] `000` = PWM Generator 1 primary trigger compare ends sampling and starts conversion[2] If SSRCG = `0`: `111` = Internal counter ends sampling and starts conversion (auto-convert) `110` = CTMU ends sampling and starts conversion `101` = Reserved `100` = Timer5 compare ends sampling and starts conversion `011` = PWM primary Special Event Trigger ends sampling and starts conversion[2] `010` = Timer3 compare ends sampling and starts conversion `001` = Active transition on the INT0 pin ends sampling and starts conversion `000` = Clearing the Sample bit (SAMP) ends sampling and starts conversion (Manual mode)
bit 4	**SSRCG:** Sample Trigger Source Group bit See SSRC<2:0> for details.
bit 3	**SIMSAM:** Simultaneous Sample Select bit (only applicable when CHPS<1:0> = `01` or `1x`) In 12-bit mode (AD21B = `1`), SIMSAM is Unimplemented and is Read as '`0`': `1` = Samples CH0, CH1, CH2, CH3 simultaneously (when CHPS<1:0> = `1x`); or samples CH0 and CH1 simultaneously (when CHPS<1:0> = `01`) `0` = Samples multiple channels individually in sequence
bit 2	**ASAM:** ADC1 Sample Auto-Start bit `1` = Sampling begins immediately after the last conversion; SAMP bit is auto-set `0` = Sampling begins when the SAMP bit is set
bit 1	**SAMP:** ADC1 Sample Enable bit `1` = ADC Sample-and-Hold amplifiers are sampling `0` = ADC Sample-and-Hold amplifiers are holding If ASAM = `0`, software can write '`1`' to begin sampling. Automatically set by hardware if ASAM = `1`. If SSRC<2:0> = `000`, software can write '`0`' to end sampling and start conversion. If SSRC<2:0> ≠ `000`, automatically cleared by hardware to end sampling and start conversion.
bit 0	**DONE:** ADC1 Conversion Status bit[3] `1` = ADC conversion cycle has completed `0` = ADC conversion has not started or is in progress Automatically set by hardware when the ADC conversion is complete. Software can write '`0`' to clear the DONE status bit (software is not allowed to write '`1`'). Clearing this bit does NOT affect any operation in progress. Automatically cleared by hardware at the start of a new conversion.

Note 1: See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for information on this selection.

2: This setting is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

3: Do not clear the DONE bit in software if Auto-Sample is enabled (ASAM = `1`).

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER(1,2) (CONTINUED)

bit 4	**OC1CS:** Clock Source for OC1 bit `1` = Generates clock pulse when the broadcast command is executed `0` = Does not generate clock pulse when the broadcast command is executed
bit 3	**OC4TSS:** Trigger/Synchronization Source for OC4 bit `1` = Generates Trigger/Synchronization when the broadcast command is executed `0` = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 2	**OC3TSS:** Trigger/Synchronization Source for OC3 bit `1` = Generates Trigger/Synchronization when the broadcast command is executed `0` = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 1	**OC2TSS:** Trigger/Synchronization Source for OC2 bit `1` = Generates Trigger/Synchronization when the broadcast command is executed `0` = Does not generate Trigger/Synchronization when the broadcast command is executed
bit 0	**OC1TSS:** Trigger/Synchronization Source for OC1 bit `1` = Generates Trigger/Synchronization when the broadcast command is executed `0` = Does not generate Trigger/Synchronization when the broadcast command is executed

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = `1` and PTGSTRT = `1`).

2: This register is only used with the `PTGCTRL OPTION` = `1111` Step command.

REGISTER 27-1: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R	R	R
DEVID<23:16>[1]							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVID<15:8>[1]							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVID<7:0>[1]							
bit 7							bit 0

Legend:	R = Read-Only bit	U = Unimplemented bit

bit 23-0 **DEVID<23:0>:** Device Identifier bits[1]

Note 1: Refer to the *“dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits”* (DS70663) for the list of device ID values.

REGISTER 27-2: DEVREV: DEVICE REVISION REGISTER

R	R	R	R	R	R	R	R
DEVREV<23:16>[1]							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVREV<15:8>[1]							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVREV<7:0>[1]							
bit 7							bit 0

Legend:	R = Read-only bit	U = Unimplemented bit

bit 23-0 **DEVREV<23:0>:** Device Revision bits[1]

Note 1: Refer to the *“dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits”* (DS70663) for the list of device revision values.

TABLE 30-14: DC CHARACTERISTICS: PROGRAM MEMORY

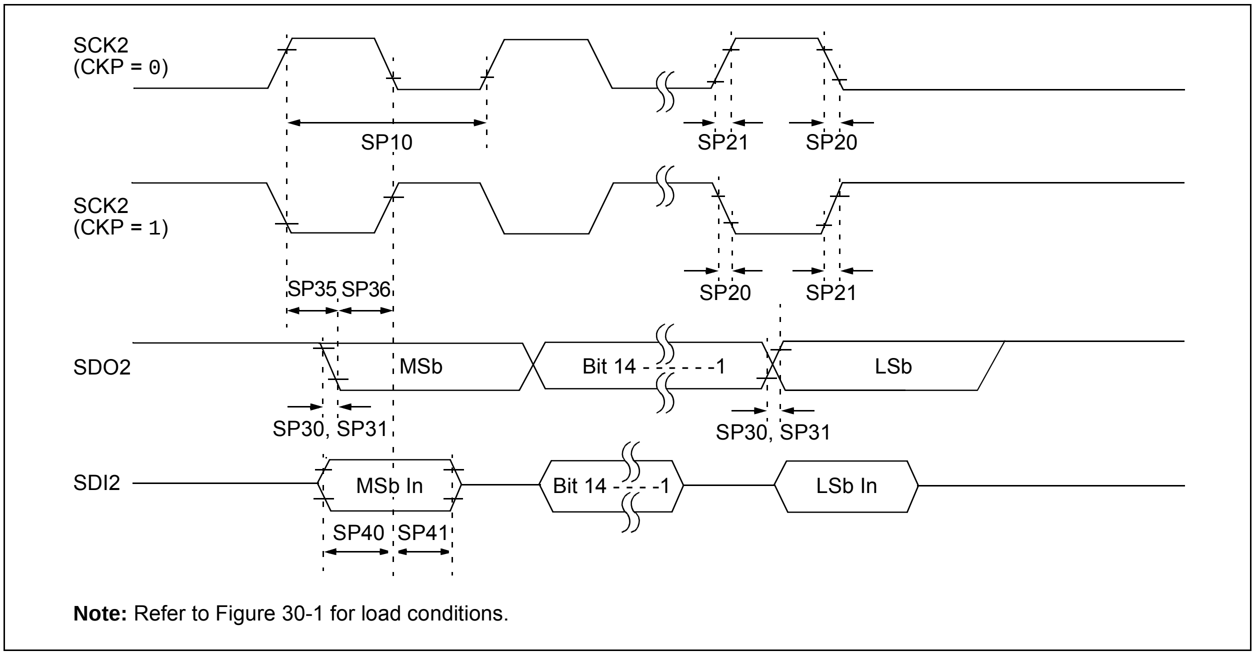
DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	3.0	—	3.6	V	
D132b	VPEW	VDD for Self-Timed Write	3.0	—	3.6	V	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current during Programming(2)	—	10	—	mA	
D136	IPEAK	Instantaneous Peak Current During Start-up	—	—	150	mA	
D137a	TPE	Page Erase Time	17.7	—	22.9	ms	TPE = 146893 FRC cycles, TA = +85°C (See **Note 3)**
D137b	TPE	Page Erase Time	17.5	—	23.1	ms	TPE = 146893 FRC cycles, TA = +125°C (See **Note 3)**
D138a	TWW	Word Write Cycle Time	41.7	—	53.8	µs	TWW = 346 FRC cycles, TA = +85°C (See **Note 3)**
D138b	TWW	Word Write Cycle Time	41.2	—	54.4	µs	TWW = 346 FRC cycles, TA = +125°C (See **Note 3)**

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Parameter characterized but not tested in manufacturing.

3: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `011111` (for Minimum), TUN<5:0> = `100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 30-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 “Programming Operations”**.

FIGURE 30-17: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-36: SPI2 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.[2]**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK2 Frequency	—	—	9	MHz	-40ºC to +125ºC **(Note 3)**
SP20	TscF	SCK2 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK2 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	

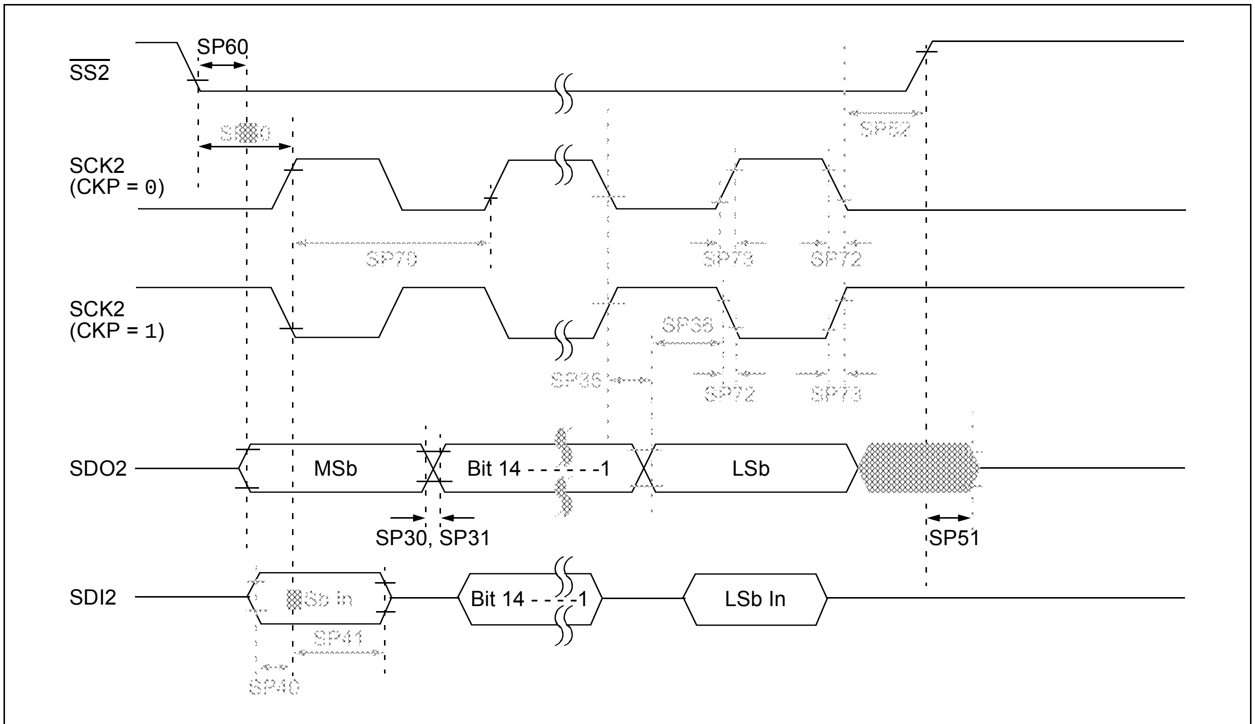
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 111 ns. The clock generated in Master mode must not violate this specification.

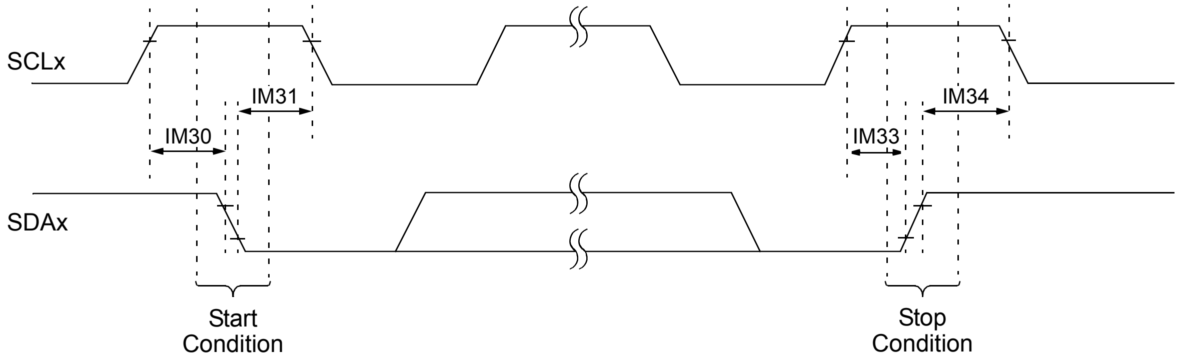
4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



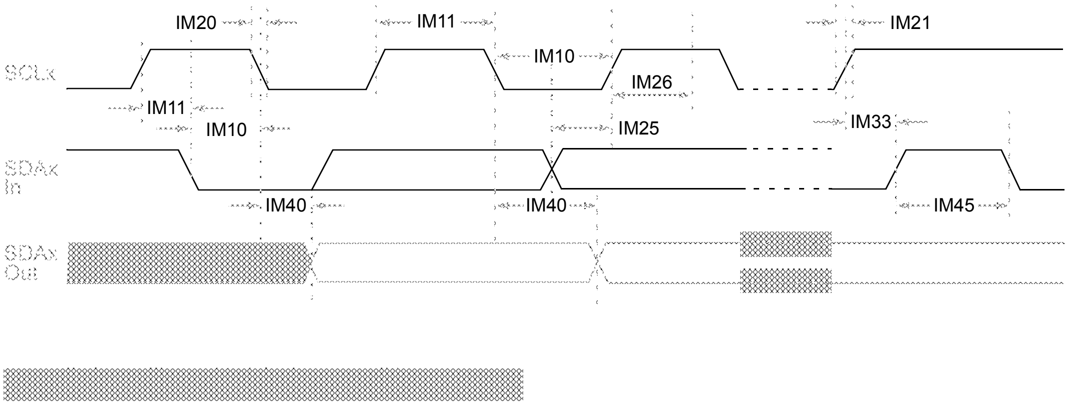
[redacted]

FIGURE 30-30: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-31: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



31.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X AC characteristics and timing parameters for high-temperature devices. However, all AC timing specifications in this section are the same as those in **Section 30.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter OS53 in **Section 30.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 31-9: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C Operating voltage VDD range as described in Table 31-1.

FIGURE 31-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

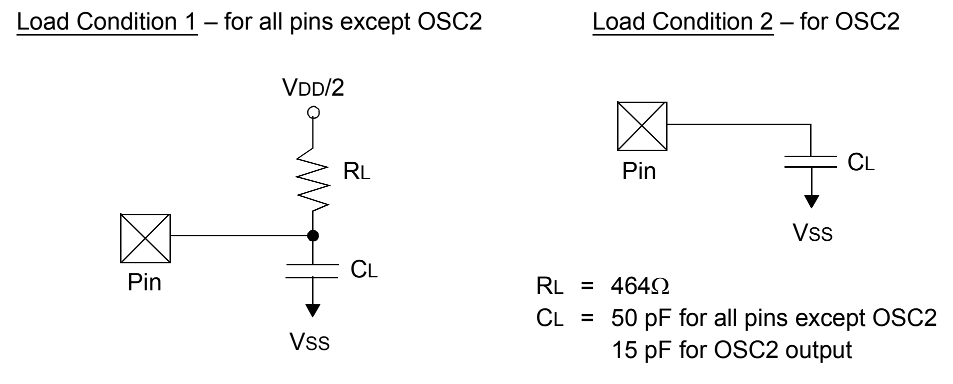


TABLE 31-10: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)[(1)]	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$\text{Peripheral Clock Jitter} = \frac{D_{CLK}}{\sqrt{\left(\frac{F_{OSC}}{\text{Peripheral Bit Rate Clock}}\right)}}$$

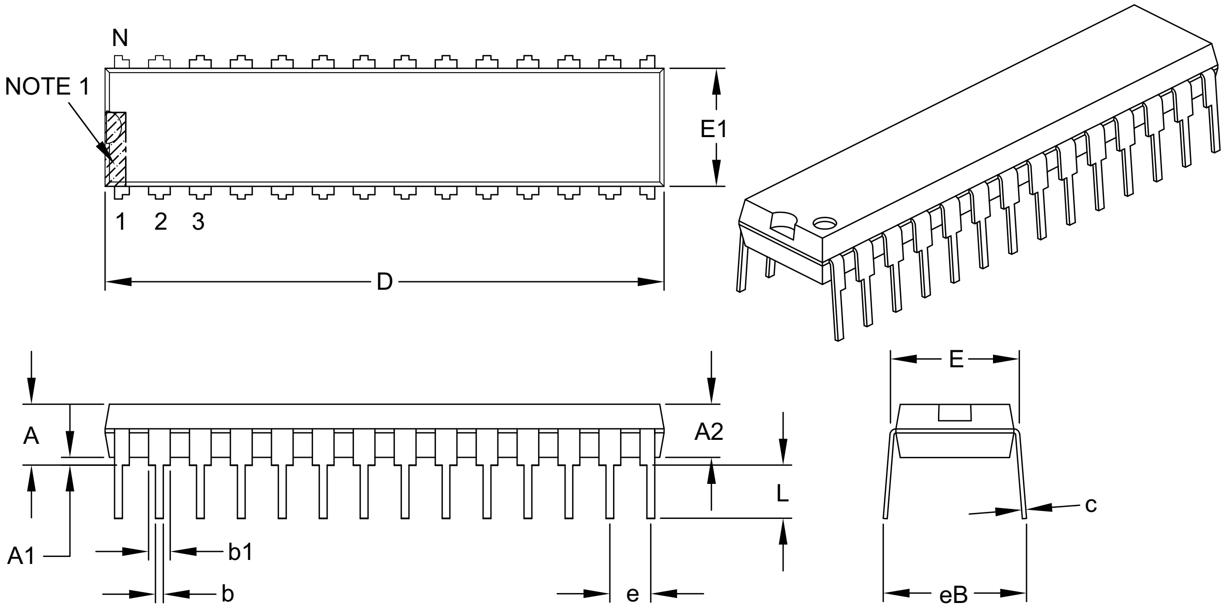
For example: FOSC = 32 MHz, DCLK = 5%, SPIx bit rate clock (i.e., SCKx) is 2 MHz.

$$\text{SPI SCK Jitter} = \left[\frac{D_{CLK}}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}}\right] = \left[\frac{5\%}{\sqrt{16}}\right] = \left[\frac{5\%}{4}\right] = 1.25\%$$

33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

    BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

Revision F (November 2012)

Removed “Preliminary” from data sheet footer.

Revision G (March 2013)

This revision includes the following global changes:

- changes “$\overline{\text{FLTx}}$” pin function to “FLTx” on all occurrences
- adds **Section 31.0 “High-Temperature Electrical Characteristics”** for high-temperature (+150°C) data

This revision also includes minor typographical and formatting changes throughout the text.

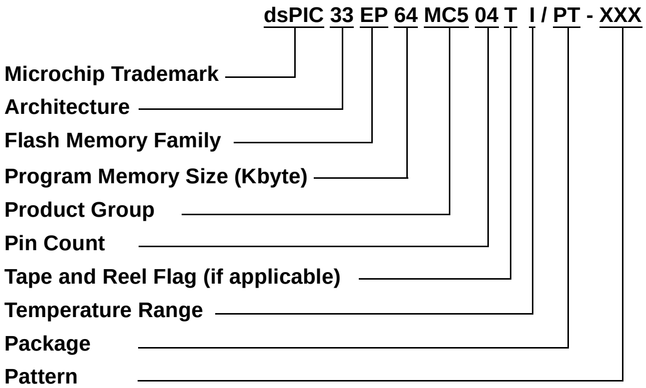
Other major changes are referenced by their respective section in Table A-5.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Changes internal oscillator specification to 1.0% • Changes I/O sink/source values to 12 mA or 6 mA • Corrects 44-pin VTLA pin diagram (pin 32 now shows as 5V tolerant)
Section 4.0 “Memory Organization”	• Deletes references to Configuration Shadow registers • Corrects the spelling of the JTAGIP and PTGWDTIP bits throughout • Corrects the Reset value of all IOCON registers as C000h • Adds footnote to Table 4-42 to indicate the absence of Comparator 3 in 28-pin devices
Section 6.0 “Resets”	• Removes references to cold and warm Resets, and clarifies the initial configuration of the device clock source on all Resets
Section 7.0 “Interrupt Controller”	• Corrects the definition of GIE as “Global Interrupt Enable” (not “General”)
Section 9.0 “Oscillator Configuration”	• Clarifies the behavior of the CF bit when cleared in software • Removes POR behavior footnotes from all control registers • Corrects the tuning range of the TUN<5:0> bits in Register 9-4 to an overall range ±1.5%
Section 13.0 “Timer2/3 and Timer4/5”	• Clarifies the presence of the ADC Trigger in 16-bit Timer3 and Timer5, as well as the 32-bit timers
Section 15.0 “Output Compare”	• Corrects the first trigger source for SYNCSEL<4:0> (OCxCON2<4:0>) as OCxRS match
Section 16.0 “High-Speed PWM Module”	• Clarifies the source of the PWM interrupts in Figure 16-1 • Corrects the Reset states of IOCONx<15:14> in Register 16-13 as ‘11’
Section 17.0 “Quadrature Encoder Interface (QEI) Module”	• Clarifies the operation of the IMV<1:0> bits (QEICON<9:8>) with updated text and additional notes • Corrects the first prescaler value for QFVDIV<2:0> (QEI1OC<13:11>), now 1:128
Section 23.0 “10-Bit/12-Bit Analog-to-Digital Converter (ADC)”	• Adds note to Figure 23-1 that Op Amp 3 is not available in 28-pin devices • Changes “sample clock” to “sample trigger” in AD1CON1 (Register 23-1) • Clarifies footnotes on op amp usage in Registers 23-5 and 23-6
Section 25.0 “Op Amp/ Comparator Module”	• Adds Note text to indicate that Comparator 3 is unavailable in 28-pin devices • Splits Figure 25-1 into two figures for clearer presentation (Figure 25-1 for Op amp/ Comparators 1 through 3, Figure 25-2 for Comparator 4). Subsequent figures are renumbered accordingly. • Corrects reference description in xxxxx (now $(AV_{DD}+AV_{SS})/2$) • Changes CMSTAT<15> in Register 25-1 to “PSIDL”
Section 27.0 “Special Features”	• Corrects the addresses of all Configuration bytes for 512 Kbyte devices

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Examples:

dsPIC33EP64MC504-I/PT:
dsPIC33, Enhanced Performance,
64-Kbyte Program Memory,
Motor Control, 44-Pin,
Industrial Temperature,
TQFP package.

Architecture:
33 = 16-bit Digital Signal Controller
24 = 16-bit Microcontroller

Flash Memory Family:
EP = Enhanced Performance

Product Group:
GP = General Purpose family
MC = Motor Control family

Pin Count:
02 = 28-pin
03 = 36-pin
04 = 44-pin
06 = 64-pin

Temperature Range:
I = -40°C to+85°C (Industrial)
E = -40°C to+125°C (Extended)

Package:
ML = Plastic Quad, No Lead Package - (44-pin) 8x8 mm body (QFN)
MM = Plastic Quad, No Lead Package - (28-pin) 6x6 mm body (QFN-S)
MR = Plastic Quad, No Lead Package - (64-pin) 9x9 mm body (QFN)
MV = Thin Quad, No Lead Package - (48-pin) 6x6 mm body (UQFN)
PT = Plastic Thin Quad Flatpack - (44-pin) 10x10 mm body (TQFP)
PT = Plastic Thin Quad Flatpack - (64-pin) 10x10 mm body (TQFP)
SO = Plastic Small Outline, Wide - (28-pin) 7.50 mm body (SOIC)
SP = Skinny Plastic Dual In-Line - (28-pin) 300 mil body (SPDIP)
SS = Plastic Shrink Small Outline - (28-pin) 5.30 mm body (SSOP)
TL = Very Thin Leadless Array - (36-pin) 5x5 mm body (VTLA)
TL = Very Thin Leadless Array - (44-pin) 6x6 mm body (VTLA)